



**MACMIC**

July 2011

**PRELIMINARY**

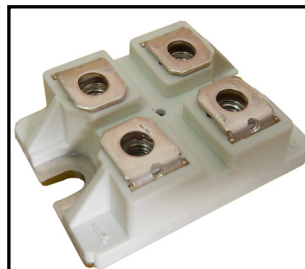
# MMF2X60J120D

1200V 60A FRED Module

RoHS Compliant

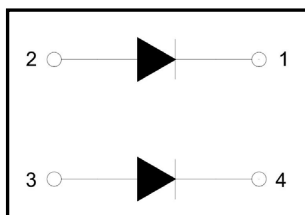
## PRODUCT FEATURES

- Ultrafast Reverse Recovery Time
- Soft Reverse Recovery Characteristics
- Low Reverse Recovery Loss
- High System Power Density
- Popular SOT-227 Package



## APPLICATIONS

- Inversion Welder
- Uninterruptible Power Supply (UPS)
- Plating Power Supply
- Ultrasonic Cleaner and Welder
- Converter & Chopper
- Power Factor Correction (PFC) Circuit



## ABSOLUTE MAXIMUM RATINGS

T<sub>C</sub>=25°C unless otherwise specified

Symbol	Parameter	Test Conditions	Values	Unit
V <sub>R</sub>	Maximum D.C. Reverse Voltage		1200	V
V <sub>R</sub> RM	Maximum Repetitive Reverse Voltage		1200	V
I <sub>F(AV)</sub>	Average Forward Current	T <sub>C</sub> =90°C, Per Diode	60	A
		T <sub>C</sub> =90°C, Per Moudle	120	A
		T <sub>C</sub> =90°C, 20KHz, Per Moudle	80	A
I <sub>F(RMS)</sub>	RMS Forward Current	T <sub>C</sub> =90°C, Per Diode	84	A
I <sub>FSM</sub>	Non-Repetitive Surge Forward Current	T <sub>J</sub> =45°C, t=10ms, 50Hz, Sine	500	A
		T <sub>J</sub> =45°C, t=8.3ms, 60Hz, Sine	550	A
I <sup>2</sup> t	I <sup>2</sup> t (For Fusing)	T <sub>J</sub> =45°C, t=10ms, 50Hz, Sine	1250	A <sup>2</sup> s
		T <sub>J</sub> =45°C, t=8.3ms, 60Hz, Sine	1512	A <sup>2</sup> s
P <sub>D</sub>	Power Dissipation		208	W
T <sub>J</sub>	Junction Temperature		-40 to +150	°C
T <sub>STG</sub>	Storage Temperature Range		-40 to +125	°C
V <sub>isol</sub>	Insulation Test Voltage	AC, t=1min	3000	V
Torque	Module-to-Sink	Recommended (M4)	0.7~1.1	N·m
Torque	Module Electrodes	Recommended (M4)	0.7~1.1	N·m
R <sub>θJC</sub>	Thermal Resistance	Junction-to-Case	0.6	°C/W
Weight			26.5	g

ELECTRICAL CHARACTERISTICS

T<sub>C</sub>=25°C unless otherwise specified

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I <sub>RM</sub>	Reverse Leakage Current	V <sub>R</sub> =1200V	--	--	0.5	mA
		V <sub>R</sub> =1200V, T <sub>J</sub> =125°C	--	--	5	mA
V <sub>F</sub>	Forward Voltage	I <sub>F</sub> =60A	--	2.10	--	V
		I <sub>F</sub> =60A, T <sub>J</sub> =125°C	--	1.75	--	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =1A, V <sub>R</sub> =30V, di <sub>F</sub> /dt=-200A/μs	--	40	--	ns
t <sub>rr</sub>	Reverse Recovery Time	V <sub>R</sub> =600V, I <sub>F</sub> =60A	--	90	--	ns
I <sub>RRM</sub>	Max. Reverse Recovery Current	di <sub>F</sub> /dt=-200A/μs, T <sub>J</sub> =25°C	--	7.5	--	A
t <sub>rr</sub>	Reverse Recovery Time	V <sub>R</sub> =600V, I <sub>F</sub> =60A	--	320	--	ns
I <sub>RRM</sub>	Max. Reverse Recovery Current	di <sub>F</sub> /dt=-200A/μs, T <sub>J</sub> =125°C	--	14	--	A

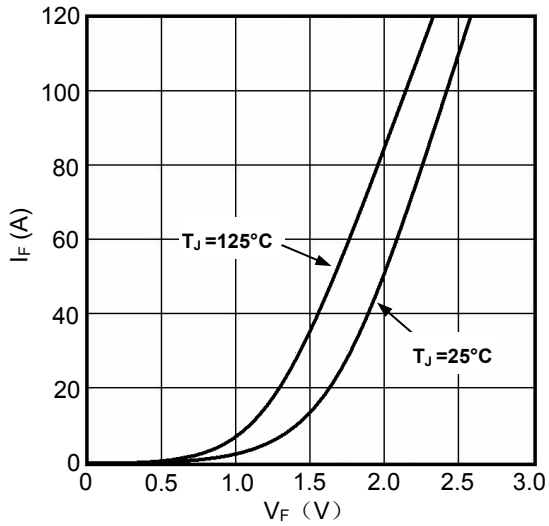


Figure1. Forward Voltage Drop vs Forward Current

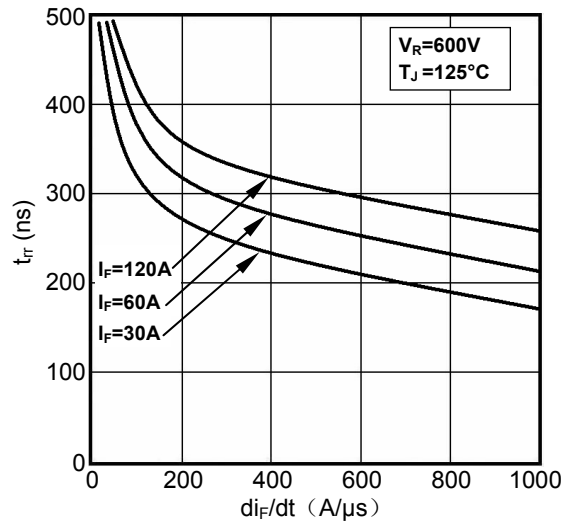


Figure2. Reverse Recovery Time vs di<sub>F</sub>/dt

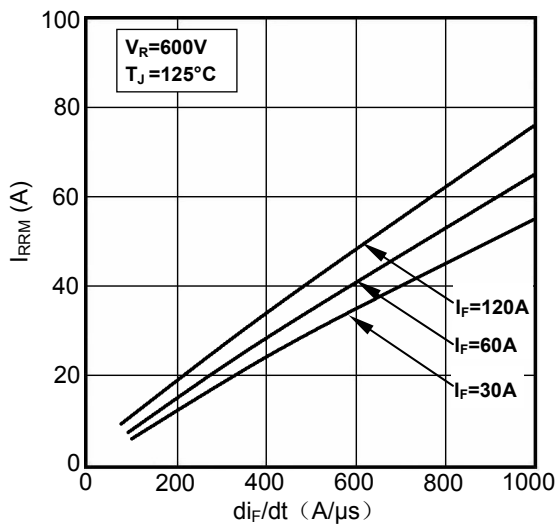


Figure3. Reverse Recovery Current vs di<sub>F</sub>/dt

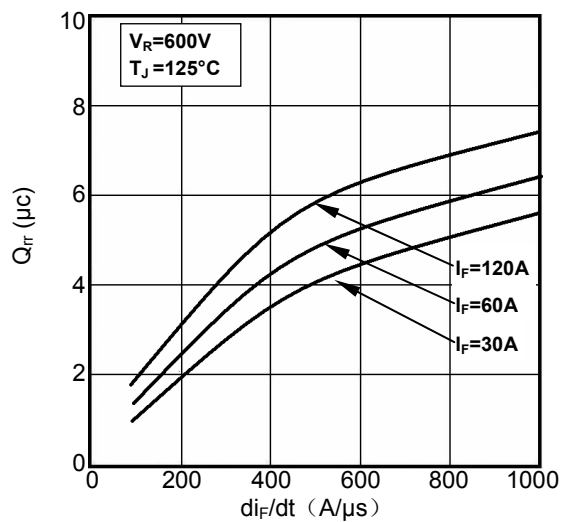


Figure4. Reverse Recovery Charge vs di<sub>F</sub>/dt

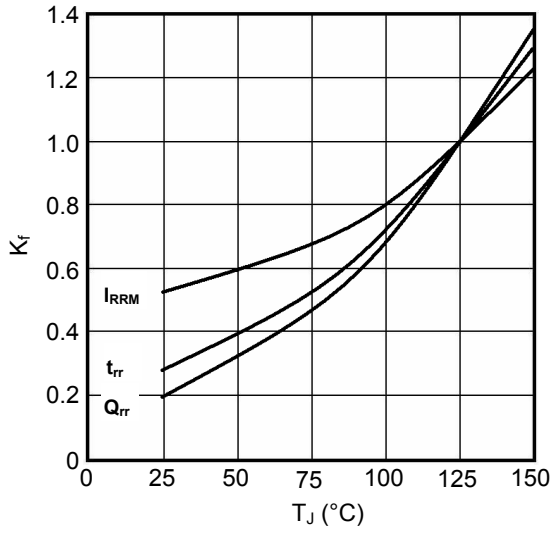


Figure5. Dynamic Parameters vs Junction Temperature

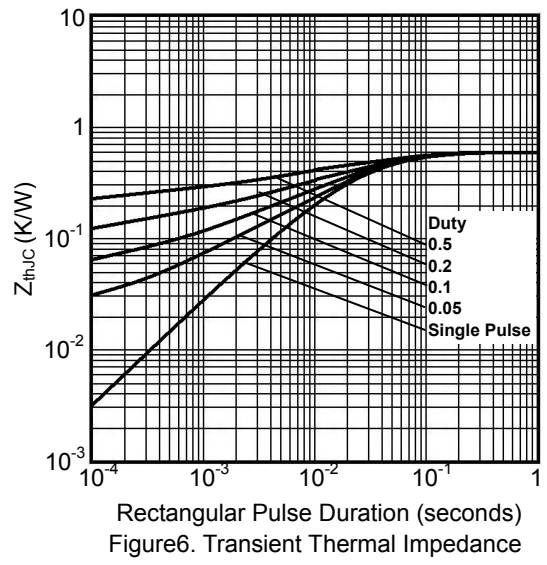
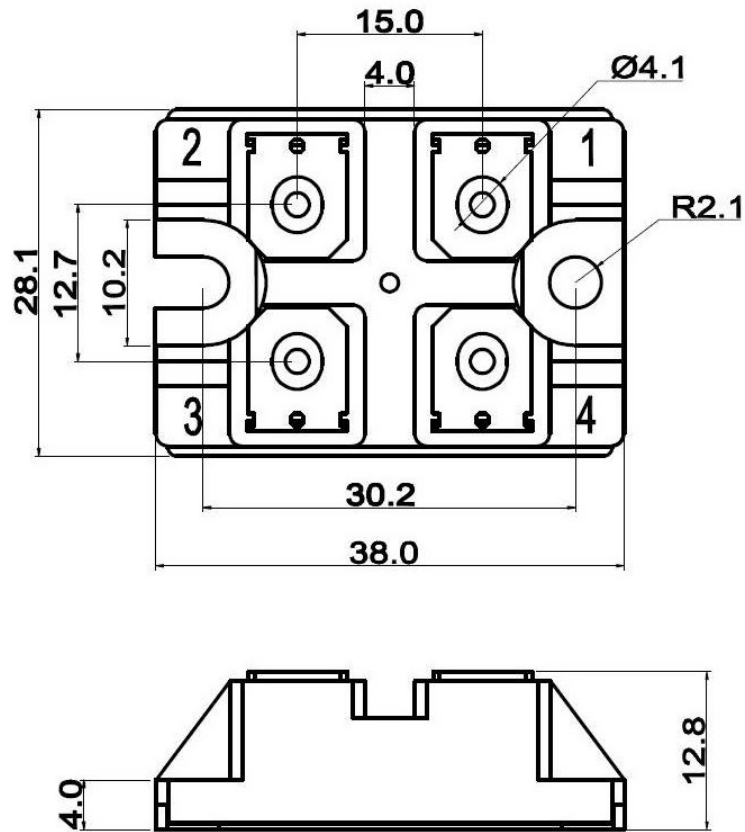


Figure6. Transient Thermal Impedance



Dimensions (mm)  
Figure7. Package Outline